Pac Tech - Packaging Technologies GmbH Appoints New Vice Presidents to Lead Business Units

Nauen, Germany – 1st March 2024

Pac Tech Packaging Technologies GmbH (PacTech), a renowned manufacturer of high-performance laser-assisted solder jetting and die bonding equipment, along with its role as a globally operating wafer level packaging subcontractor, proudly announces the internal promotions of Ms. Sy Jiun Sim and Mr. Matthias Fettke as Vice Presidents to lead key business units.

Dr. Thorsten Teutsch, CEO of PacTech, expressed his vision for the company's future, stating, "Our intent is to strengthen our engineering leverage through 2024, enhancing middle management and leadership across all business units and sites. We are incredibly proud to recognize the exceptional talents of Sy Jiun and Matthias, who have been cultivated within PacTech. This decision reflects our commitment to nurturing and advancing internal talent to drive our strategic initiatives forward."

Ms. Sim began her journey with PacTech as a Customer Support Manager at the Penang subcon site in 2010, subsequently transitioning to PacTech's headquarters in Germany as Marketing Manager in 2017. With a master's degree in project management, Ms. Sim will now lead PacTech's Wafer Level Packaging business units in Southeast Asia and Germany, overseeing the expansion and ramp-up of WLP services utilizing cutting-edge electroless and electroplating process technologies.

Mr. Fettke, who holds a master's degree in Laser & Opto-Technology with a specialization in laser material processing, has been instrumental in innovating new laser bonding and soldering technologies at PacTech. He possesses a broad skill set that includes research and development, manufacturing, and product management in the photonics and semiconductor industries. His contributions have led to numerous publications and patents. In his new role as Vice President of Advanced Packaging Equipment, Mr. Fettke will lead the equipment business unit to further advance PacTech's technological capabilities.

About PacTech

PacTech is a global leader in advanced wafer bumping, packaging, and solder ball placement equipment. The SB2 solder jetting equipment offers unique flux-less and contact-less soldering solutions for camera modules, THT, HDD, and other advanced packaging applications. The Laplace machine platform provides laser automated bonding and reflow solutions along the heterogeneous integration roadmap for packaging of thermally or geometrically challenged semiconductor chips. Additionally, the PacLine series offers high-performance, electroless plating batch systems for fully automated processing of ≥ 300mm wafers. PacTech caters to various markets, including compound semiconductor, photonics, power, 5G, microLED, and MEMS.

PacTech also provides plating chemistries and high-volume subcontractor bumping and die prep services from its manufacturing facilities in Germany (HQ), the USA, and Malaysia.

For more information, please contact:

Thomas Oppert
Vice President Global Equipment Sales
Email: oppert@pactech.de